

Application Number 10/573717
Response to the Office Action dated 12/14/2007

REMARKS

Favorable reconsideration of this application is requested in view of the following remarks.

Claim 1 has been amended as supported by the specification at page 17, line 27 – page 18, line 6 and Figures 1 and 3D.

Claim 24 has been cancelled without prejudice.

Claim 24 has been rejected under 35 U.S.C. 102(b) as being anticipated by Nakatani et al. (U.S. Patent No. 7,068,519). Applicants respectfully traverse this rejection.

Applicants cancel claim 24. Therefore, this rejection is moot, and accordingly, this rejection should be withdrawn. Applicants are not conceding the correctness of the rejection.

Claims 1-5 have been rejected under 35 U.S.C. 103(a) as being unpatentable over Kanzawa et al. (U.S. Patent Application Publication No. 2004/0078969) in view of Kwong (U.S. Patent No. 6,732,428). Applicants respectfully traverse this rejection.

Kanzawa does not disclose or suggest a first electrical insulating sheet with a cavity formed penetrating therethrough for mounting an electronic component, and a second electrical insulating sheet formed by lamination over the first sheet to cover the cavity, as claim 1 requires. Instead of mounting the electronic component in the cavity in the insulating sheet, the reference discloses that the electronic component is placed directly on the circuit pattern on one insulating sheet or on electroconductive projecting electrodes, which are formed on the electronic component by using an adhesive or by heating and pressing with using a film (see paras. 80 and 84 and Fig. 10) on an projecting electrodes. Subsequently, an insulating resin is injected into the gap between the electronic component and the base (see para. 81 and Fig. 11), and then, an electrical

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insulating sheet without the electronic component is superposed on the insulating sheet including the electronic component, or vice versa, followed by a heating and pressing step (see para. 82 and Figs. 12 and 13). Therefore, the method of mounting the electronic component in claim 1, in which firstly, a cavity is formed by lamination and secondly, the electronic component is mounted in that cavity, is distinguished from the reference. Accordingly, Kanzawa, which does not form a cavity to mount the electronic component, does not disclose or suggest a step of altering a shape of the cavity to fix the electronic component and at the same time, connecting the wiring patterns through a via conductor by applying heat and pressure to the insulating sheet.

Kwong discloses a cavity (176) penetrating through an insulating sheet (see Fig. 2). However, a size of the cavity of Kwong has been determined before mounting an electronic component and is unchanged after the mounting and is such as to coincide precisely with the outer dimensions of an electronic component to be mounted or to be somewhat larger than the size of the electronic component so as to allow ambient air to assist in cooling or the cavity having formed as a channel through which air may be forced to assist in cooling the electronic component (see coln. 9, lines 43-55; and Fig. 2). In contrast, claim 1 requires steps of laminating a second insulating sheet over the first sheet with a cavity to cover the cavity, which determines a size of the cavity, mounting an electronic component, and thereafter altering a shape of the cavity to fix the electronic component in the insulating sheet and simultaneously, connecting the wiring patterns by applying heat and pressure to the insulating sheet, that the reference does not disclose or suggest. Therefore, Kwong does not remedy the deficiencies of Kanzawa.

Accordingly, this rejection of claims 1-5 should be withdrawn.

Claim 6 has been rejected under 35 U.S.C. 103(a) as being unpatentable over Kanzawa et al. (U.S. Patent Application Publication No. 2004/0078969) in view of Kwong (U.S. Patent No. 6,732,428) and further in view of Hirano et al. (U.S. Patent No. 7,022,276). Applicants respectfully traverse this rejection.

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Hirano does not remedy the deficiencies of Kanzawa in view of Kwong, and accordingly, the rejection of claim 6 should be withdrawn. Applicants do not concede the correctness of the rejection.

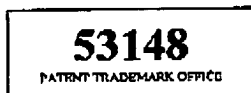
Claim 9 has been rejected under 35 U.S.C. 103(a) as being unpatentable over Kanzawa et al. (U.S. Patent Application Publication No. 2004/0078969) in view of Kwong (U.S. Patent No. 6,732,428) and further in view of Sugaya et al. (U.S. Patent No. 6,931,725). Applicants respectfully traverse this rejection.

Sugaya does not remedy the deficiencies of Kanzawa in view of Kwong, and accordingly, the rejection of claim 9 should be withdrawn. Applicants do not concede the correctness of the rejection.

Claims 10-16 and 17-23 have been objected to as being dependent upon a rejected base claim. Applicants respectfully traverse this objection.

Claim 1 that is the base claim of claims 10-16 and 17-23 should be allowable as discussed above. Therefore, this objection should be withdrawn. Applicants do not concede with the correctness of the objection.

In view of the above, Applicants request reconsideration of the application in the form of a Notice of Allowance.



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DPM/my/ad

Respectfully submitted,

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